

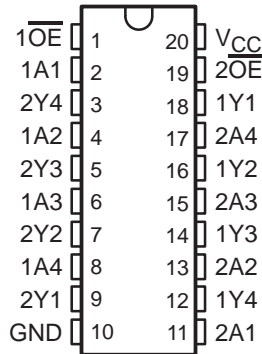
SN74LVT244B

3.3-V ABT OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

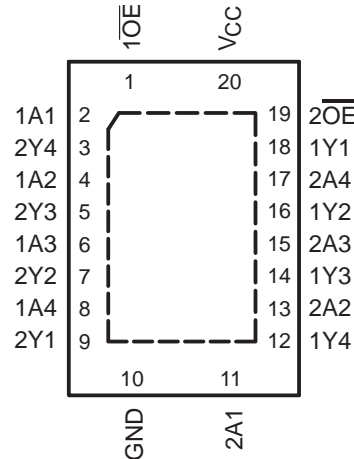
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- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Supports Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DB, DW, NS, OR PW PACKAGE
(TOP VIEW)



RGY PACKAGE
(TOP VIEW)



description/ordering information

This octal buffer and line driver is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVT244B is organized as two 4-bit line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74LVT244BRGYR	LX244B
	SOIC – DW	Tube	SN74LVT244BDW	LVT244B
		Tape and reel	SN74LVT244BDWR	
	SOP – NS	Tape and reel	SN74LVT244BNSR	LVT244B
	SSOP – DB	Tape and reel	SN74LVT244BDBR	LX244B
	TSSOP – PW	Tube	SN74LVT244BPW	LX244B
		Tape and reel	SN74LVT244BPWR	
	VFBGA – GQN	Tape and reel	SN74LVT244BGQNR	LX244B
VFBGA – ZQN (Pb-free)	SN74LVT244BZQNR			

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN74LVT244B

3.3-V ABT OCTAL BUFFER/DRIVER

WITH 3-STATE OUTPUTS

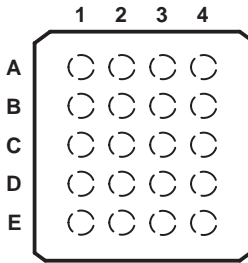
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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

GQN OR ZQN PACKAGE
(TOP VIEW)



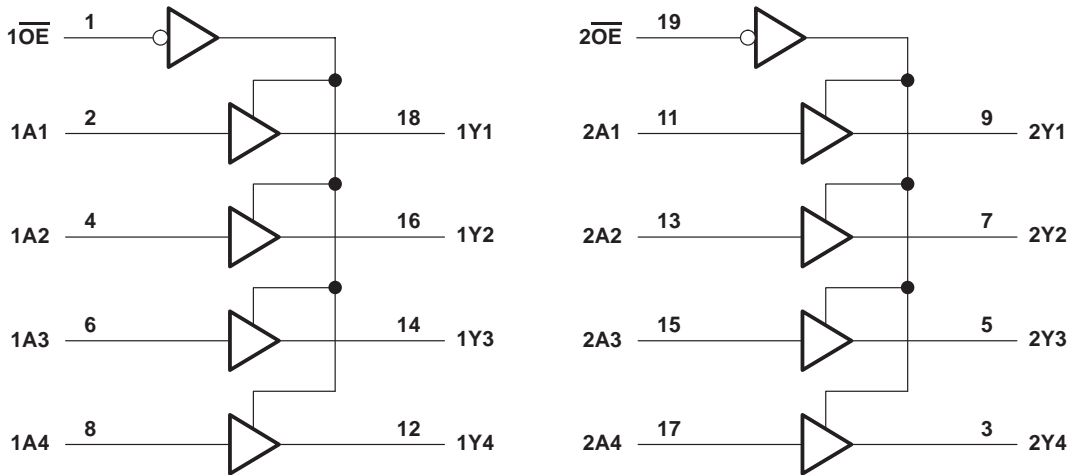
terminal assignments

	1	2	3	4
A	1A1	$\overline{1OE}$	V_{CC}	$\overline{2OE}$
B	1A2	2A4	2Y4	1Y1
C	1A3	2Y3	2A3	1Y2
D	1A4	2A2	2Y2	1Y3
E	GND	2Y1	2A1	1Y4

FUNCTION TABLE
(each 4-bit buffer)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, NS, PW, and RGY packages.

SN74LVT244B
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SCAS354J – FEBRUARY 1994 – REVISED SEPTEMBER 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O	128 mA
Current into any output in the high state, I_O (see Note 2)	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3): DB package	70°C/W
(see Note 3): DW package	58°C/W
(see Note 3): GQN/ZQN package	78°C/W
(see Note 3): NS package	60°C/W
(see Note 3): PW package	83°C/W
(see Note 4): RGY package	37°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51-7.
4. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 5)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.7	3.6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage		5.5	V
I_{OH}	High-level output current		–32	mA
I_{OL}	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
	Outputs enabled			
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		μs/V
T_A	Operating free-air temperature	–40	85	°C

NOTE 5: All unused inputs of the device must at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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SCAS354J – FEBRUARY 1994 – REVISED SEPTEMBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}		V _{CC} = 2.7 V,	I _I = -18 mA			-1.2	V
V _{OH}		V _{CC} = 2.7 V to 3.6 V,	I _{OH} = -100 μA	V _{CC} -0.2			V
		V _{CC} = 2.7 V,	I _{OH} = -8 mA	2.4			
		V _{CC} = 3 V,	I _{OH} = -32 mA	2			
V _{OL}		V _{CC} = 2.7 V		I _{OL} = 100 μA		0.2	V
				I _{OL} = 24 mA		0.5	
		V _{CC} = 3 V		I _{OL} = 16 mA		0.4	
				I _{OL} = 32 mA		0.5	
				I _{OL} = 64 mA		0.55	
I _I	Control inputs	V _{CC} = 0 or 3.6 V,	V _I = 5.5 V			10	μA
		V _{CC} = 3.6 V,	V _I = V _{CC} or GND			±1	
	Data inputs	V _{CC} = 3.6 V	V _I = V _{CC}			1	
			V _I = 0			-5	
I _{off}		V _{CC} = 0,	V _I or V _O = 0 to 4.5 V			±100	μA
I _{OZH}		V _{CC} = 3.6 V,	V _O = 3 V			5	μA
I _{OZL}		V _{CC} = 3.6 V,	V _O = 0.5 V			-5	μA
I _{OZPU}		V _{CC} = 0 to 1.5 V, V _O = 0.5 V to 3 V, \overline{OE} = don't care				±100	μA
I _{OZPD}		V _{CC} = 1.5 V to 0, V _O = 0.5 V to 3 V, \overline{OE} = don't care				±100	μA
I _{CC}	V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND		Outputs high			0.19	mA
			Outputs low			5	
			Outputs disabled			0.19	
ΔI _{CC} ‡	V _{CC} = 3 V to 3.6 V, One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND					0.2	mA
C _i	V _I = 3 V or 0					4	pF
C _o	V _O = 3 V or 0					7	pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

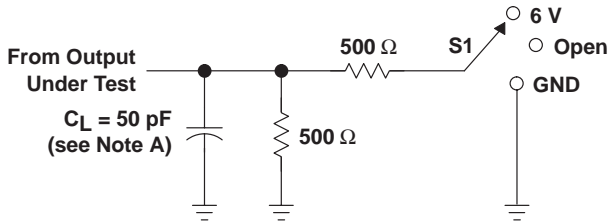
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
t _{PLH}	A	Y	1.1	2.3	3.5	3.8		ns
t _{PHL}			1.3	2.1	3.3	3.6		
t _{PZH}	\overline{OE}	Y	1.1	2.5	4.5	5.3		ns
t _{PZL}			1.4	2.7	4.4	4.9		
t _{PHZ}	\overline{OE}	Y	1.9	2.8	4.4	4.5		ns
t _{PLZ}			1.8	2.9	4.4	4.4		

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

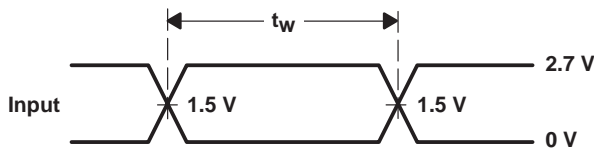


PARAMETER MEASUREMENT INFORMATION

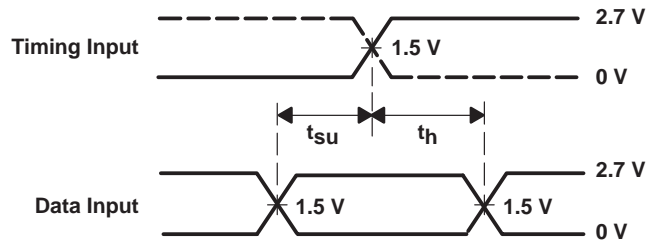


LOAD CIRCUIT

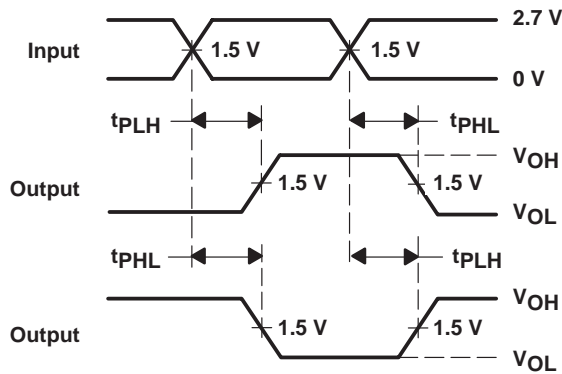
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



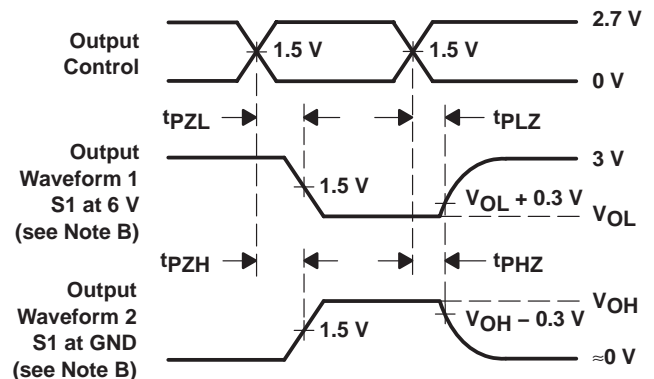
**VOLTAGE WAVEFORMS
PULSE DURATION**



**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**



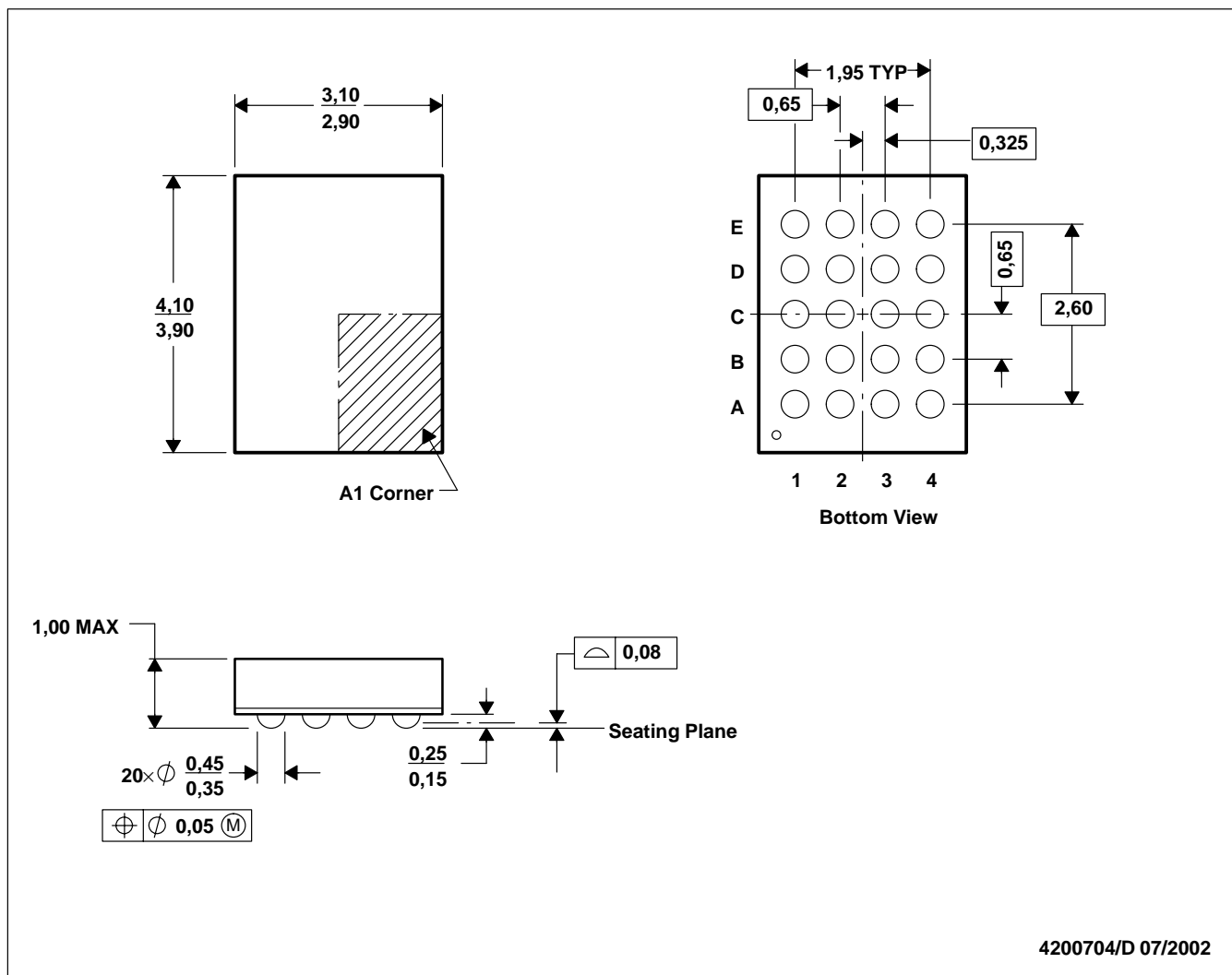
**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 D. The outputs are measured one at a time with one transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY

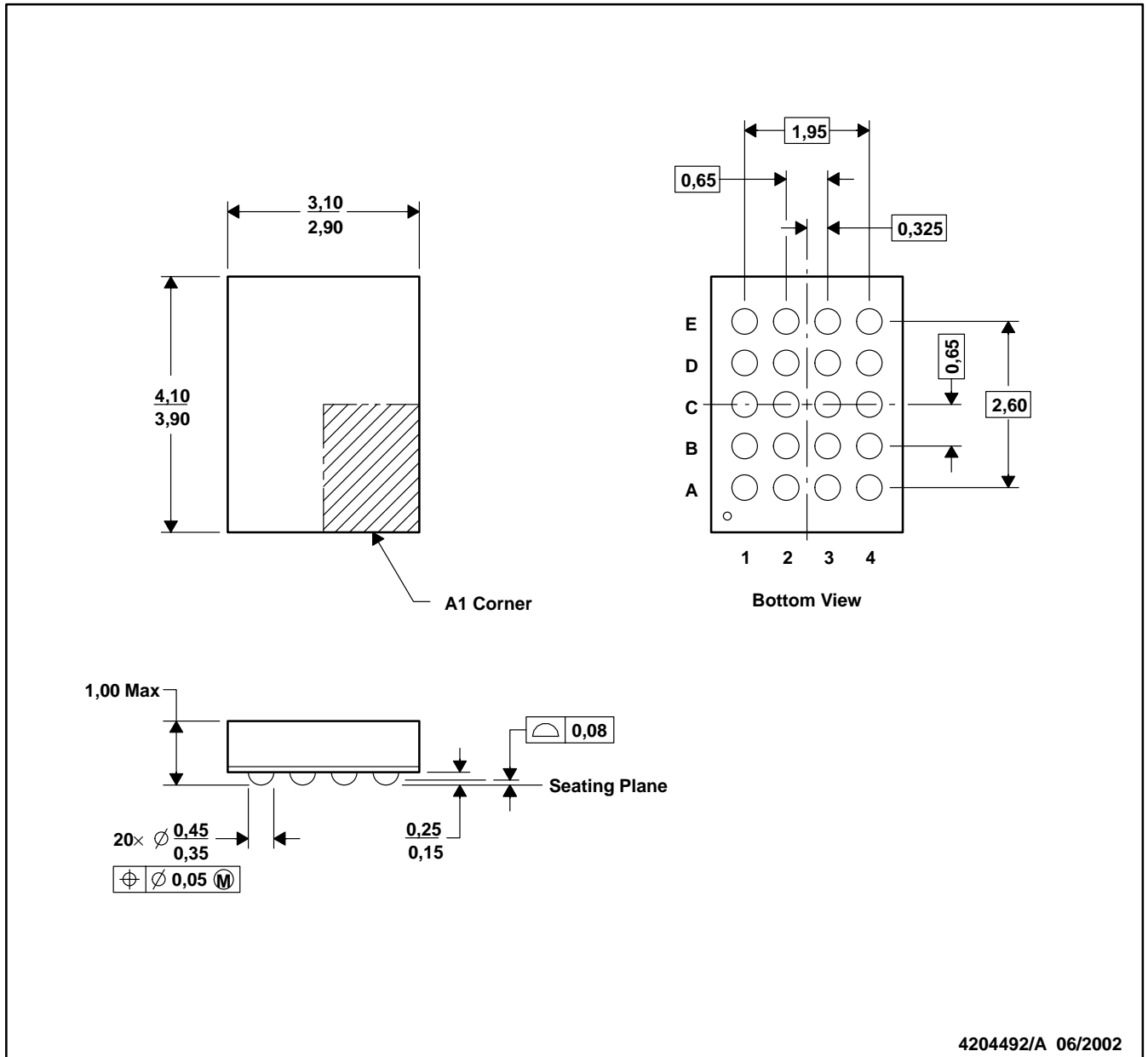


- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - MicroStar Junior™ configuration
 - Falls within JEDEC MO-225 variation BC.
 - This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

MicroStar Junior is a trademark of Texas Instruments.

ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY

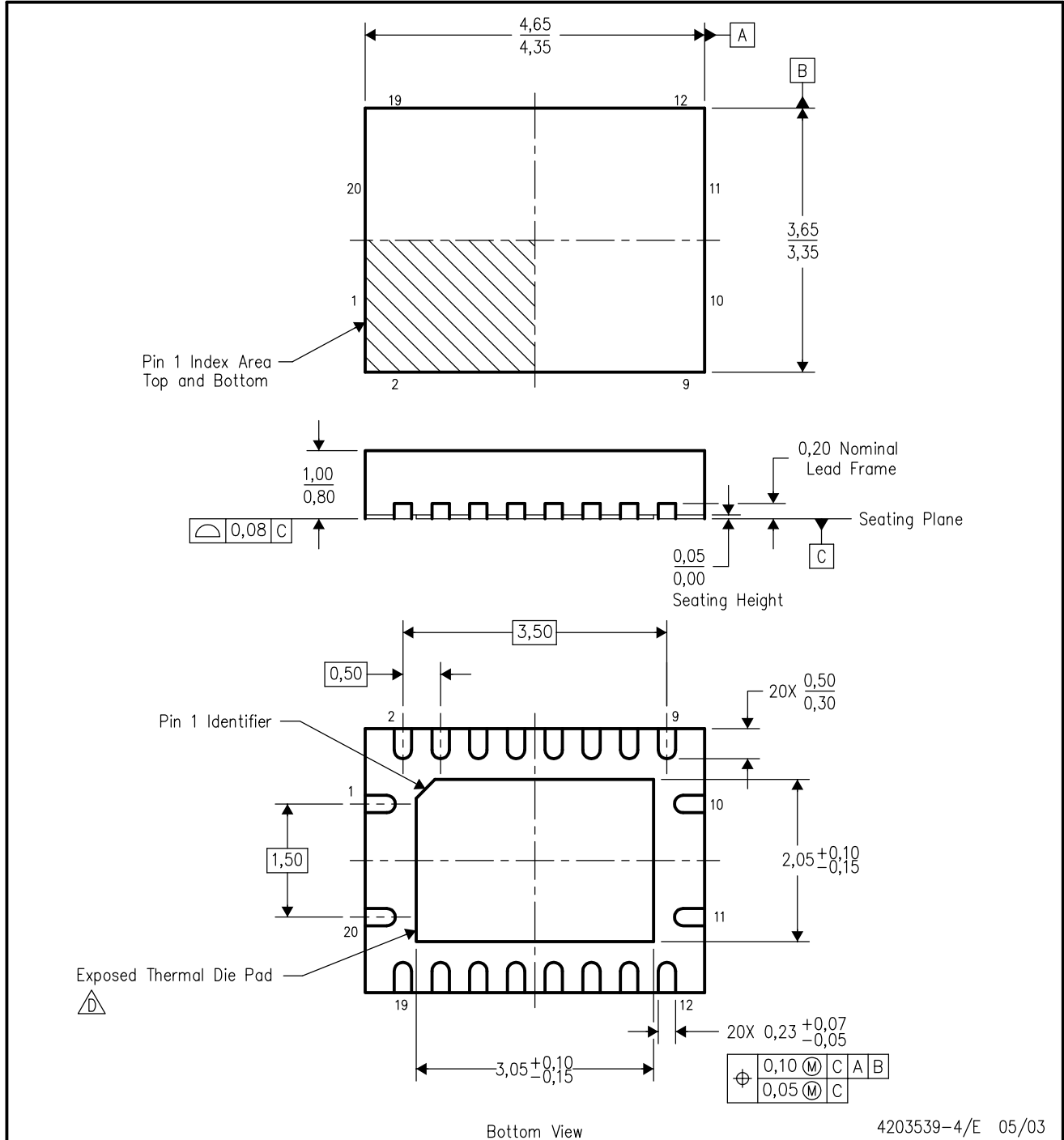



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - MicroStar Junior™ configuration.
 - Fall within JEDEC MO-225 variation BC.
 - This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

MicroStar Junior is a trademark of Texas Instruments.

RGY (R-PQFP-N20)

PLASTIC QUAD FLATPACK

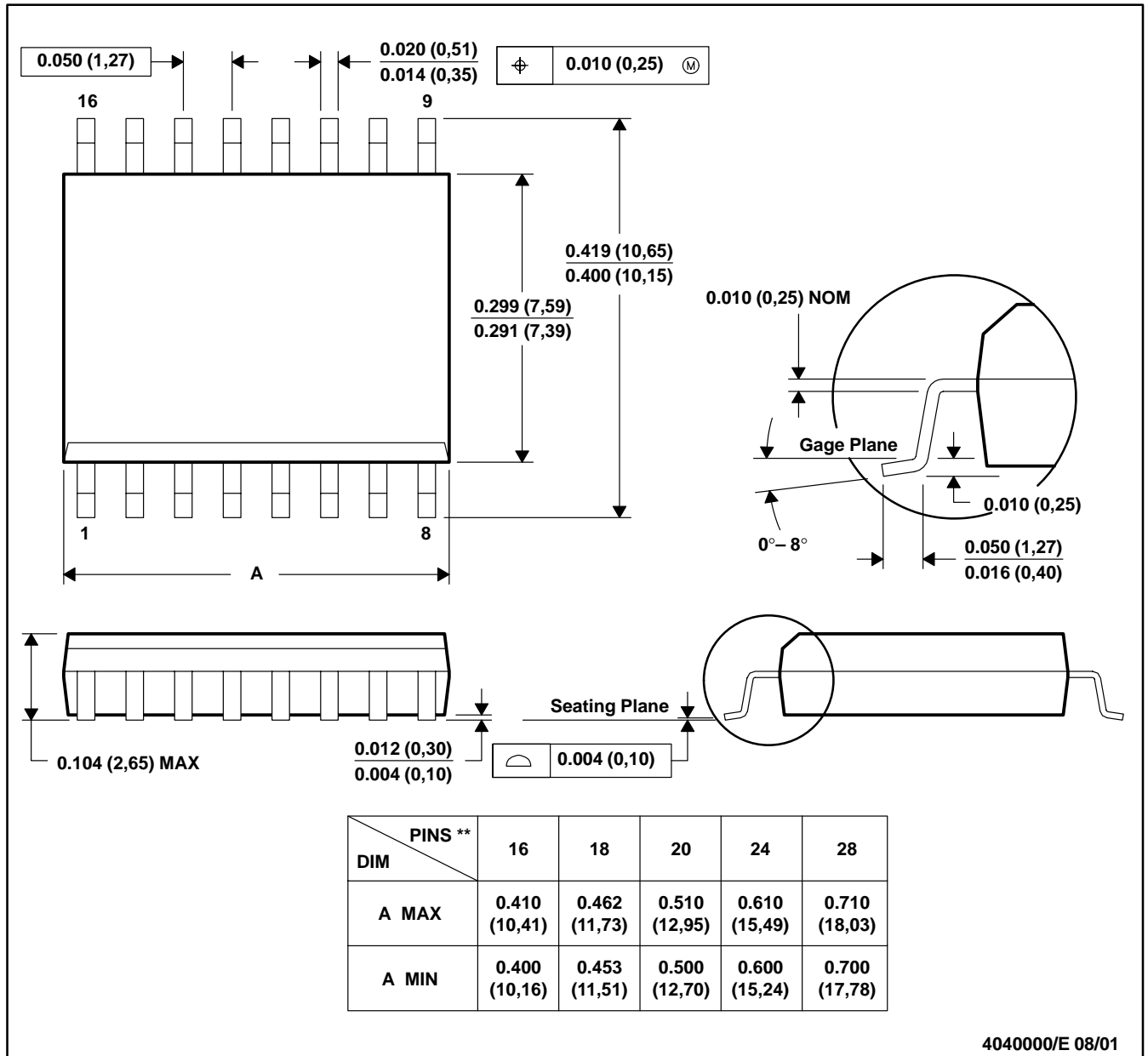


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 -  The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BC.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



4040000/E 08/01

- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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